

[제24회] 한국반도체 학술대회] Final Program at a Glance

2월 13일(월)		Room A	Room B	Room C
		에메랄드 (2층)	토파즈 (2층)	사파이어 (2층)
14:00-18:00	240'	[Short Course 1] Optical Technologies for Metrology and Inspection	[Short Course 2] 2D 반도체소재의 특성 및 응용	[Short Course 3] Neuromorphic 소자 및 활용

2월 14일(화)		Room A	Room B	Room C	Room D	Room E	Room F	Room G	Room H	Room I	로비	
		2층					3층					
		에메랄드	토파즈	사파이어	크리스탈	루비	제이드	코랄	다이아몬드1	다이아몬드2	로비	
08:30-10:00	90'	[TA1-D] Hybrid Oxide Thin Films	[TB1-K] Unconventional Approaches in Resistance Switching Memories	[TC1-G] Device Physics and Characterization 1	[TD1-S] Chip Design Contest	[TE1-F] Advanced CMOS Devices I		[TG1-J] Graphene base Nanofabrications (08:30-10:30)			전시 Chip Design Contest CDC 관람시간 (Core Session)	
10:00-10:10	10'	휴식 (& 커피, 다과)										
10:10-11:40	90'	[TA2-D] Emerging Thin Film Technology	[TB2-K] Dielectric, Ferromagnetic, and Phase Change Materials for Memory Application	[TC2-G] Reliability Analysis	[TD2-E] WBG High Frequency Device	[TE2-F] Advanced CMOS Devices II		[TG2-J] Two-Dimensional Materials beyond Graphene (10:40-11:40)				
11:40-13:00	80'	점심 [포시즌 / 1층]										
13:00-14:00	60'	Plenary Session 1 [다이아몬드1 / 3층]: 정은승 부사장 (삼성전자 반도체연구소장) "The Present and Future of Semiconductor Technology"										
14:00-15:00	60'	Plenary Session 2 [다이아몬드1 / 3층]: Dr. Geoffrey W. Burr (IBM Almaden Research Center, USA) "Neuromorphic Technologies for Next-Generation Cognitive Computing"										
15:00-16:00	60'											[TP1] 포스터세션1
16:00-17:30	90'	[TA3-D] Oxide Thin Film Transistors	[TB3-H] Display and Imaging Technologies	[TC3-G] Device Modeling and Simulation 1	[TD3-E] WBG Power Device	[TE3-F] Advanced CMOS Materials	[TF3-R] Semiconductor Software 1	[TG3-J] Two-Dimensional Materials beyond Graphene				
18:00-20:00	120'	만찬 [다이아몬드1 / 3층]										
20:00-22:00	120'	Rump Session 1 [에메랄드 / 2층] 저전력 인공지능을 위한 뉴로모픽 기술의 전망 Rump Session 2 [토파즈 / 2층] Smart Cars: The Next Growth Engine for the Semiconductor Industry Rump Session 3 [사파이어 / 2층] 반도체 스케일링의 향후 전망과 기술 과제										

2월 15일(수)		Room A	Room B	Room C	Room D	Room E	Room F	Room G	Room H	Room I	로비	
		2층					3층					
		에메랄드	토파즈	사파이어	크리스탈	루비	제이드	코랄	다이아몬드 1	다이아몬드2	로비	
08:30-10:00	90'	[WA1-D] Thin Films for Memories and Transistors	[WB1-A] Packaging and Design	[WC1-G] Device Physics and Characterization 2	[WD1-I] Flexible Sensors	[WE1-F] Advanced CMOS Processing and Reliability	[WF1-B] Plasma and Patterning Processes	[WG1-C] Materials Growth & Characterization I	[WH1-O] VLSI System Design and Applications 1		전시	
10:00-10:10	10'	휴식 (& 커피, 다과)										
10:10-11:40	90'	[WA2-D] 2D Materials and Devices	[WB2-A] Process issues of Interconnect	[WC2-G] Device Modeling and Simulation 2	[WD2-I] Bio/Gas/Pressure sensors	[WE2-F] Flash and Si Memory Technologies	[WF2-B] Patterning and Lithography	[WG2-C] Materials Growth & Characterization II	[WH2-O] VLSI System Design and Applications 2			
11:40-12:40	60'	점심 [포시즌 / 1층]										
12:40-14:25	105'	[WA3-D] ALD/CVD Thin Films	[WB3-K] Resistance Switching Memories	[WC3-Q] Metrology and Inspection (I)	[WD3-I] FET-based sensors	[WE3-F] Advanced CMOS Integrated Circuits	[WF3-R] Semiconductor Software 2	[WG3-J] Nanofabrication for Next Generation Device Applications	[WH3-M] RF and Wireless System and Components			
14:25-15:25	60'											[WP1] 포스터세션2
15:25-17:10	105'	[WA4-P] Materials and Devices for Energy	[WB4-K] Understanding Resistance Switching Phenomena	[WC4-Q] Metrology and Inspection (II)	[WD4-E] WBG Characterization Technology	[WE4-L] Analog Circuit Design	[WF4-R] Semiconductor Software 3	[WG4-J] Nanofabrication for Next Generation Device Applications	[WH4-N] Advances in Design Automation and Test			